

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

## Title of Invention

Adapter Board for Stacking Ball-Grid-Array (BGA) chips

Application Number :

Confirmation Number:

First Named Applicant: Yao Yen

Attorney Docket Number: PS-108

Art Unit:

Examiner:

Search string: ( 6587393 or 6576992 or 6461895 or 6414381 or 6339254 or 6157080 or 5910010 or 5744827 or 20030107118 or 20030081392 or 20030001288 ),pn

## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6587393	2003-07-01	Ayukawa , et al.	B1	365	230.03
	2	6576992	2003-06-10	Cady , et al.	B1	257	686
	3	6461895	2002-10-08	Liang , et al.	B1	438	107
	4	6414381	2002-07-02	Takeda	B1	257	676
	5	6339254	2002-01-15	Venkateshwaran , et al. January 15, 2002	B1	257	686
	6	6157080	2000-12-05	Tamaki , et al.	B1	257	738
	7	5910010	1999-06-08	Nishizawa , et al.	B1	438	15
	8	5744827	1998-04-28	Jeong , et al.	B1	257	686

## US Published Applications

**Note: Applicant is not required to submit a paper copy of cited US Published Applications**

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030107118	2003-06-12	Pflughaupt, L. Elliott ; et al.	A1	257	686
	2	20030081392	2003-05-01	Cady, James W. ; et al.	A1	361	767
	3	20030001288	2003-01-02	Tay, Wu Yean ; et al.	A1	257	780

**Signature**

Examiner Name	Date